100% Material Declaration Data Sheet TQG144

Average Weight: 1.4 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					**0.0147**	**1.05%**
	Silicon	7440-21-3	100.00		0.0147	
Die Attach Material					**0.00224**	**0.16%**
	Silver	7440-22-4	78.00		0.0017472	
	Epoxy (EP)	Trade Secret	22.00		0.0004928	
Mold Compound					**1.10208**	**78.72%**
	Epoxy Resin (EP)	Trade Secret	9.00		0.0991872	
	Phenolic Resin	Trade Secret	7.00		0.0771456	
	Carbon Black	1333-86-4	0.50		0.0055104	
	Silica	60676-86-0	82.50		0.909216	
	Bismuth	7440-69-9	Max 1.00		0.0110208	
Leadframe					**0.26124**	**18.66%**
	Copper	7440-50-8	98.85		0.25823574	
	Chromium	7440-47-3	0.30		0.00078372	
	Tin	7440-31-5	0.25		0.0006531	
	Zinc	7440-66-6	0.60		0.00156744	
Leadframe Plating					**0.00112**	**0.08%**
	Silver	7440-22-4	100.00		0.00112	
Bond Wire					**0.00616**	**0.44%**
	Gold	7440-57-5	100.00		0.00616	
Ext. Plating					**0.01246**	**0.89%**
	Tin	7440-31-5	100.00		0.01246	

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Xilinx believes this environmental information to be correct, but cannot guarantee its completeness or accuracy as it is based on data received from sources outside our company.

Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
2/09/06	1.0	Initial release.
7/10/06	1.1	100% Material Declaration.
9/28/06	1.2	Updated component descriptions.
10/19/06	1.2.1	Editorial change; corrected typo in Substance Description.